

What is claimed is:

1. A sensor device comprising:  
an electronic sensor for outputting an electric signal in accordance  
5 with physical displacement of a sensing portion;  
a casing in which said electronic sensor is mounted; and  
a vibration damping member provided between at least part of said  
electronic sensor and said casing for damping high-frequency vibration.
- 10 2. The sensor device in accordance with claim 1, wherein said  
vibration damping member is a potting material, and said electronic sensor  
is surrounded by said potting material.
- 15 3. The sensor device in accordance with claim 1, wherein said  
vibration damping member is a plate or sheet vibration proofing material or  
a molded vibration proofing material integrated together with said electronic  
sensor, and said electronic sensor is fixed to said casing via said vibration  
proofing material.
- 20 4. The sensor device in accordance with claim 1, wherein said  
vibration damping member is a lead member having elasticity which is  
connected to said electronic sensor at least at a portion thereof and is fixed  
to said casing at least at the other portion thereof, and said lead member and  
said electronic sensor are arranged so as to cooperatively constitute a  
25 spring-mass system consisting of spring of said lead member and mass of  
said electronic sensor for damping high-frequency vibration.
5. The sensor device in accordance with claim 4, wherein said lead  
member is integrally molded with said casing.

30

6. The sensor device in accordance with claim 1, wherein said electronic sensor includes a detecting portion, a communicating portion, and an electric power source circuit integrated together as one package, and is directly attached to said casing.

5

7. The sensor device in accordance with claim 1, wherein said electronic sensor is mounted on a substrate, and said substrate is attached to said casing.

10

8. The sensor device in accordance with claim 1, wherein setting of physical properties including hardness and dielectric dissipation factor, as well as shape and size of said vibration damping member is determined so as to enhance the properties for damping high-frequency vibration including a resonance point of said electronic sensor.

15

9. An electronic component mounting ceramic package for mounting electronic components, comprising:

a metallic electrode allowing post-welding is provided on a main body of the ceramic package.

20

10. The electronic component mounting ceramic package in accordance with claim 9, wherein said metallic electrode is brazed to said main body of the ceramic package.

25

11. A sensor device comprising;  
an electronic sensor for outputting an electric signal in accordance with physical displacement of a sensing portion; and  
a casing in which said electronic sensor is mounted,  
wherein casing comprises:

30

a primary molded portion formed by primary molding so as to

surround said electronic sensor with a first resin material capable of damping high-frequency vibration, and

5 a secondary molded portion formed by secondary molding so as to surround said primary molded portion with a second resin material harder than said first resin material.

12. The sensor device in accordance with claim 11, wherein said first resin material is a liquid-state silicone rubber.

10 13. A sensor device, comprising:  
an electronic sensor for outputting an electric signal in accordance with physical displacement of a sensing portion; and  
a casing in which said electronic sensor is mounted,  
wherein said casing is made of a resin material containing a vibration  
15 damping material capable of damping high-frequency vibration.

14. The sensor device in accordance with claim 13, wherein said electronic sensor is integrally molded with said resin material containing the vibration damping material.

20 15. The sensor device in accordance with claim 13, wherein said vibration damping material is a thermoplastic elastomer.

16. A sensor device comprising:  
25 an electronic sensor for outputting an electric signal in accordance with physical displacement of a sensing portion;  
a casing in which said electronic sensor is mounted; and  
a dynamic damper attached to said electronic sensor, and said dynamic damper being tuned to a resonance point of said sensing portion.

30

17. The sensor device in accordance with claim 16, wherein said dynamic damper is made of a plate or sheet elastic member.